WUXI XUYANG ELECTRONICS CO., LTD.

US1A THRU US1M

SURFACE MOUNT ULTRA FAST SWITCHING RECTIFIER

TECHNICAL SPECIFICATION

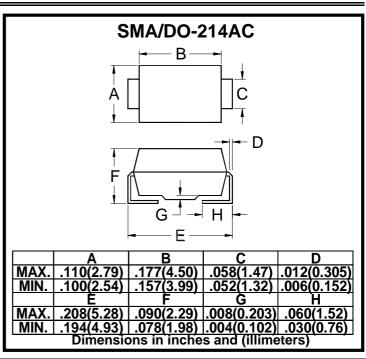
VOLTAGE: 50 TO 1000V CURRENT: 1.0A

FEATURES

- Ideal for surface mount pick and place application
- Low profile package
- Built-in strain relief
- High surge capability
- Glass passivated chip
- Ultra fast recovery for high efficiency
- High temperature soldering guaranteed: 260°C/10sec/at terminal

MECHANICAL DATA

- Terminal: Plated leads solderable per MIL-STD 202E, method 208C
- Case: Molded with UL-94 Class V-O recognized flame retardant epoxy
- Polarity: Color band denotes cathode



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Single-phase, half-wave, 60Hz, resistive or inductive load rating at 25°C, unless otherwise stated, for capacitive load, derate current by 20%)

RATINGS		SYMBOL	US	US	US	US	US	US	US	UNITS
			1A	1B	1D	1G	1J	1K	1M	
Maximum Repetitive Peak Reverse Voltag	je	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Curr	rent		1.0							۸
(T _L =100°C)		I _{F(AV)}								Α
Peak Forward Surge Current (8.3ms single	k Forward Surge Current (8.3ms single		30							Α
half sine-wave superimposed on rated load)		'FSM								
Maximum Instantaneous Forward Voltage (at rated forward current)		V_{F}	1.0 1.4			1.7			V	
		▼ F							•	
Maximum DC Reverse Current T _a =2	25°C	1	5.0						μΑ	
(at rated DC blocking voltage) T _a =10	00°C	I _R	200							μΑ
Maximum Reverse Recovery Time (Not	te 1)	trr	50				75			nS
Typical Junction Capacitance (Not	te 2)	C_{J}	20				10			pF
Typical Thermal Resistance (Not	te 3)	$R_{\theta}(ja)$	32						°C/W	
Storage and Operation Junction Temperate	ure	T_{STG},T_{J}	-50 to +150						°C	
Note:										•

Note

- 1.Reverse recovery condition I_E=0.5A, I_R=1.0A,Irr=0.25A.
- 2.Measured at 1.0 MHz and applied voltage of 4.0V_{dc}
- 3. Thermal resistance from junction to terminal mounted on 5×5mm copper pad area